LNJ037X8BRA

Hight Bright Surface Mounting Chip LED

ESS II Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

9 a				
Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	40	mW	
Forward current	I _F	10	mA	
Pulse forward current *	I _{FP}	40	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

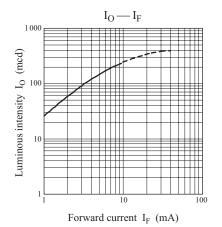
Lighting Color

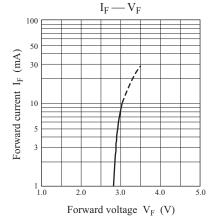
• White

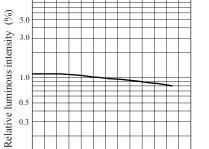
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity I _O	т	$I_F = 1 \text{ mA}$	18.0	29.0	45.0	mcd
	IO	$(I_F = 5 \text{ mA})$	(80)	(150)	(205)	mcd
Reverse current	I _R	$V_R = 5 V$			10	μΑ
Forward voltage	V _F	$I_F = 1 \text{ mA}$	2.6	2.8	3.0	V
Chromaticity coordinates x y	X	$I_F = 1 \text{ mA}$	0.220		0.281	
	у	$I_F = 1 \text{ mA}$	0.187		0.272	







30

Ambient temperature T_a (°C)

 $I_F - T_a$

30

60

0

60

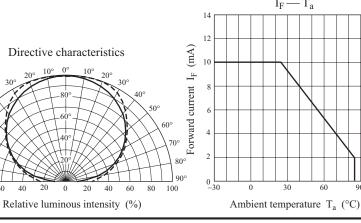
90

Та

Relative luminous intensity -

10.0

0.1



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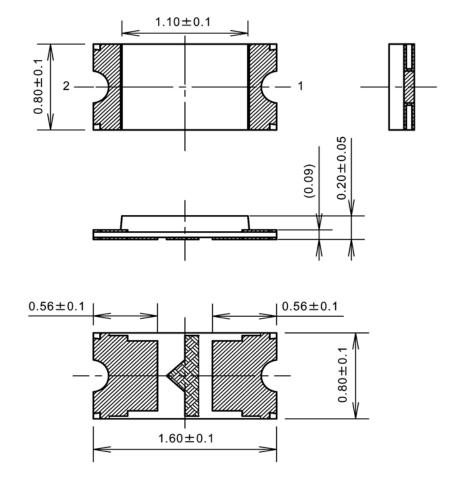
70

80

90°

100 80 60 90

Package (Unit: mm)



• Pin Name

1: Anode

2: Cathode

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